

ABSTRACT OF THE DISCLOSURE

A function module with a built-in plate-type heat dissipation device. The function module includes a first circuit board, a second circuit board, and a plate-type heat dissipation device. The first circuit board includes a first surface with a first ground layer formed thereon. The second circuit board is coupled to the first circuit board, and includes a second surface facing the first surface. A second ground layer is formed on the second surface. The plate-type heat dissipation device is disposed between the first circuit board and the second circuit board, and abuts the first ground layer and the second ground layer respectively.